ZZ1. Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ2. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3. These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ4. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Components marked 'DNP' should not be populated.
Assembly Variant: 001

PCB VIEWED FROM TOP SIDE

<table>
<thead>
<tr>
<th>IGNORE -&gt;</th>
<th>Top Assembly Drawing</th>
<th>BOARD #: TIDA-00307</th>
<th>REV: E2</th>
<th>SUN REV: Not In Version Control</th>
</tr>
</thead>
<tbody>
<tr>
<td>TopSolder</td>
<td>Top Assembly Drawing</td>
<td>GENERATED: 9/18/2014</td>
<td>1:38:30 PM</td>
<td>TEXAS INSTRUMENTS</td>
</tr>
</tbody>
</table>
COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001
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